

IMCOM 2027

21

International Conference on Ubiquitous Information Management and Communication

January 04-06, 2027

Taipei, Taiwan (Offline and Online)

<http://www.imcom.org>

The conference proceedings are Scopus and EI indexed. Accepted papers will be submitted for possible inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements. **Selected papers** presented at the conference will be published after further improvement and revision at Special Issues in IEEE Access, WCMC, Oxford The Computer Journal, IEEE Transactions on Emerging Topics in Computing, IET Intelligent Transport Systems, along with 5 other SCI/SCIE journals.



General Information

This conference will constitute a forum for the presentation and discussion of the latest results in the fields of information management, communication technologies and their implications on social interaction. The aim of such a forum, as an international conference, is conducive for encouraging the exchange of ideas and information, providing research directions in cutting-edge domains, and fostering collaborations between academia and industry. In this context, the program committee will accept a limited number of papers that meet the criteria of originality and presentation quality.

Two main tracks for information processing management and communication technologies will be held, covering both research and applicability aspects. Each of these topic areas is expanded below but their sub-topics are not listed exhaustively.

Information Processing Management

Information Management

- ✓ Internet search/ Security/ Privacy
- ✓ Portals/ UCC management/ Social media management
- ✓ Online communities/ Social networks
- ✓ Databases/ XML/ Data mining/ Big data
- ✓ Information integration/ Data warehousing
- ✓ Information personalization/ Recommendation systems
- ✓ O2O/ W2W/ B2B and B2C
- ✓ E-commerce and m-commerce

Intelligent Information Processing

- ✓ Machine learning/ Deep learning
- ✓ Computer vision/ Generative AI
- ✓ Situational awareness/ Contextual Intelligence
- ✓ Autonomous computing/ Self-adaptive systems
- ✓ Natural language processing/ Conversational AI
- ✓ Interactive intelligence/ Sentiment analysis
- ✓ Cognitive AI and robotics
- ✓ Pattern recognition
- ✓ Expert system/ Knowledge graphs

Interaction Management

- ✓ Interaction systems/ Multimodal interaction
- ✓ Augmented reality/ Virtual reality / Gaming
- ✓ Human-drone interaction/ Robotics
- ✓ Multimedia visualization/ Computer graphics
- ✓ Speech recognition and synthesis
- ✓ Facial recognition/ Emotion detection
- ✓ Pervasive computing/ Ambient intelligence
- ✓ Biometrics/ Wearables/ Sensor technology

Communications

Networking/ Telecommunications

- ✓ NextGen network protocols
- ✓ AI communications and networking
- ✓ Intelligent cross-layer optimization
- ✓ Reliability and quality assurance
- ✓ Industrial/ Healthcare/ Environmental IoT
- ✓ Cloud/ Edge/ Fog computing and services
- ✓ Deterministic/ Time-sensitive networking
- ✓ Network softwarization technologies
- ✓ Zero-touch orchestration
- ✓ Energy harvesting and green networking

Social Interaction

- ✓ Social computing/ Informatics/ Social web
- ✓ Virtual reality/ Augmented reality/ Mixed reality
- ✓ Gamification/ Serious games/ Game design
- ✓ Mobile Interaction/ Mobile apps/ Wearable technology
- ✓ Cyberpsychology/ Engineering psychology
- ✓ Computational modeling/ Computational thinking/ Computational creativity
- ✓ Personalization/ User profiling
- ✓ Human-robot interaction/ Robot ethics/ Robot design
- ✓ User-centered design/ User research/ Design thinking

Important Dates

Paper submission due: September 16, 2026
 Paper acceptance notice: October 15, 2026
 Paper registration due: October 31, 2026
 Camera-ready papers due: November 15, 2026

SCOPUS Engineering Village

Submission Guidelines

Regular Papers/Short Papers: Camera-ready version of regular and short papers should not be longer than 8 and 4 pages in IEEE proceedings format, respectively. Accepted papers will be categorized into oral paper or poster paper. Both will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements and considered for Journal recommendation. For guidelines on paper submissions, please refer to <http://www.imcom.org>

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